

Special Issue

Advances in Microelectronic Materials, Processes and Devices

Message from the Guest Editor

Silicon microelectronics is at the heart of modern electronics, finding applications in computing, data processing, data storage, communications or internet-of-things field. Its development has been guided by Moore's law since the 70's and is nowadays reaching its physical limits related to device dimension, integration density and complexity both in CMOS and memory technologies. To overcome these limits, new challenges have been addressed regarding new material integration for FEOL and BEOL purpose, new processes for material growth, deposition, doping, etching and patterning, new device architectures for better scalability, improved physical characterization techniques for CD metrology, advanced device and interconnect electrical characterization methodologies. We invite researcher to contribute works on the "Advances in Microelectronic Materials, Processes and Devices" topic. Potential subjects include, but are not limited to:

- New material;
- Integration processes;
- Device architectures;
- Physical characterization and metrology;
- Electrical characterization and reliability;

Guest Editor

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Deadline for manuscript submissions

closed (31 March 2022)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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